

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Arvind Kumar</td><td>09/04/2006</td></tr><tr><td>Keen Wah Chow</td><td>09/04/2006</td></tr><tr><td>Devesh Kumar Datta</td><td>09/04/2006</td></tr><tr><td>Subramanian Krishnan</td><td>09/04/2006</td></tr></tbody></table>	Name	Execution Date	Arvind Kumar	09/04/2006	Keen Wah Chow	09/04/2006	Devesh Kumar Datta	09/04/2006	Subramanian Krishnan	09/04/2006	
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Arvind Kumar	09/04/2006										
Keen Wah Chow	09/04/2006										
Devesh Kumar Datta	09/04/2006										
Subramanian Krishnan	09/04/2006										
RECEIVING PARTY DATA											
Name:	TECH Semiconductor Singapore Pte. Ltd.										
Street Address:	No. 1 Woodlands Industrial Park D, Street 1										
City:	Singapore										
State/Country:	SINGAPORE										
Postal Code:	738799										
PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11515534</td></tr></tbody></table>	Property Type	Number	Application Number:	11515534							
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Application Number:	11515534										
CORRESPONDENCE DATA											
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Total Attachments: 2 source=TE06-001#page1.tif											

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PATENT  
REEL: 018386 FRAME: 0491



TE06-001

For ☒ U.S. and/or ☒ Foreign Rights  
For ☒ Application or ☐ U.S. Patent  
By ☒ Inventor(s) or ☐ Present Owner

### ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

#### ASSIGNOR:

**ARVIND KUMAR**

Type or print name of ASSIGNOR

Blk 513, Woodlands Dr 14, #12-191

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Indian

Nationality

**KEEN WAH CHOW**

Type or print name of ASSIGNOR

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Malaysian

Nationality

**DEVESH KUMAR DATTA**

Type or print name of ASSIGNOR

Blk 802, Woodlands Street 81, #04-79

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Nationality

**SUBRAMANIAN KRISHNAN**

Type or print name of ASSIGNOR

46 Canberra Drive, Yishun Sapphire

Address

Singapore 768436

Indian

Nationality

hereby sells, assigns and transfers to

#### ASSIGNEE:

**TECH Semiconductor Singapore Pte. Ltd.**

**No. 1 Woodlands Industrial Park D**

**Street 1**

**Singapore 738799**

**Singapore**

Nationality

and the successors, assigns and legal representatives of the ASSIGNEE

(complete one of the following)

☒ the entire right, title and interest

☐ an undivided \_\_\_\_\_ percent (\_\_\_\_%) interest for the United States and its territorial possessions

(check the following box/f foreign rights are also to be assigned)

☒ and in all foreign countries

in and to any and all improvements which are disclosed in the invention entitled:

**Method For Passivation Of Plasma Etch Defects In DRAM Devices**

and which is found in

- ☒ (a) U.S. patent application executed on even date herewith
- ☐ (b) U.S. patent application executed on \_\_\_\_\_
- ☐ (c) U.S. application serial no. \_\_\_\_\_ filed on \_\_\_\_\_
- ☐ (d) U.S. patent no. \_\_\_\_\_ issued \_\_\_\_\_  
(also check (e) if foreign application(s) is also being assigned)
- ☒ (e) and any legal equivalent thereof in a foreign country, including the right to claim priority

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute, thereof, and as to letters patent any re-issue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I / We have signed this

4 Sept 2006 (Date of signing)

WARNING Date of signing must be the same as the date of execution of the application if item (a) was checked above.

Signature of ASSIGNOR(S)

[Signature]  
[Signature]  
Derek R. Ball  
S. Kuroh

If ASSIGNOR is a legal entity complete the following information

\_\_\_\_\_  
Type or print the name of the above person authorized to sign on behalf of ASSIGNOR

\_\_\_\_\_  
Title

Note: No witnessing, notarization or legalization is necessary, if the assignment is notarized or legalized then it will only be prima facie evidence (35 USC 261). Use next page if notarization is desired.

\_\_\_\_\_  
Notarization of Legalization Page Added.